imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NL27WZ16

Dual Buffer

The NL27WZ16 is a high performance dual buffer operating from a 1.65 to 5.5 V supply. At $V_{CC} = 3$ V, high impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance.

Features

- Extremely High Speed: t_{PD} 2.0 ns (typical) at V_{CC} = 5 V
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability With 5 V TTL Logic with V_{CC} = 3 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

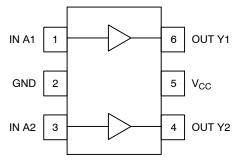


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS







= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

| Pin | Function |
|-----|-----------------|
| 1 | IN A1 |
| 2 | GND |
| 3 | IN A2 |
| 4 | OUT Y2 |
| 5 | V _{CC} |
| 6 | OUT Y1 |

FUNCTION TABLE

| A Input | Y Output |
|---------|-----------------|
| L | L |
| Н | Н |

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

| Symbol | Characteristics | Value | Units |
|----------------------|---|---------------------------|-------|
| V _{CC} | DC Supply Voltage | -0.5 to +7.0 | V |
| VI | DC Input Voltage | $-0.5 \le V_{l} \le +7.0$ | V |
| V _O | DC Output Voltage Output in Z or LOW State (Note 1) | $-0.5 \le V_0 \le +7.0$ | V |
| I _{IK} | DC Input Diode Current V _I < GND | -50 | mA |
| Ι _{ΟΚ} | DC Output Diode Current V _O < GND | -50 | mA |
| lo | DC Output Sink Current | ±50 | mA |
| I _{CC} | DC Supply Current per Supply Pin | ±100 | mA |
| I _{GND} | DC Ground Current per Ground Pin | ±100 | mA |
| T _{STG} | Storage Temperature Range | -65 to +150 | °C |
| P _D | Power Dissipation in Still Air SC-88, TSOP-6 | 200 | mW |
| θ_{JA} | Thermal Resistance SC-88, TSOP-6 | 333 | °C/W |
| ΤL | Lead Temperature, 1 mm from Case for 10 Seconds | 260 | °C |
| TJ | Junction Temperature Under Bias | +150 | °C |
| V _{ESD} | ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4) | > 2000 > 200 N/A | V |
| I _{Latchup} | Latchup Performance Above V_{CC} and Below GND at 85°C (Note 5) | ±500 | mA |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
1. I_O absolute maximum rating must be observed.
2. Tested to EIA/JESD22-A114-A
3. Tested to EIA/JESD22-A115-A
4. Tested to EIA/JESD22-A115-A

Tested to JESD22–C101–A
 Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Units |
|-----------------|--|------------------|---------------------|-------|
| V _{CC} | Supply Voltage Operating Data Retention Only | 1.65 1.5 | 5.5 5.5 | V |
| VI | Input Voltage | 0 | 5.5 | V |
| Vo | Output Voltage (High or LOW State) | 0 | 5.5 | V |
| T _A | Operating Free-Air Temperature | -55 | +125 | °C |
| Δt/ΔV | | 0 0 0 0 | 20 20 10 5 | ns/V |

DC ELECTRICAL CHARACTERISTICS

| | | | V _{cc} | Т | A = 25° | С | –55°C ≤ T | A ≤ 125°C | |
|------------------|---|--|----------------------------------|---|--|---|---|---|-------|
| Symbol | Parameter | Condition | (V) | Min | Тур | Max | Min | Max | Units |
| V _{IH} | High-Level Input Voltage | | 1.65 to 1.95 2.3 to 5.5 | 0.75 V _{CC} 0.7 V _{CC} | | | 0.75 V _{CC} 0.7 V _{CC} | | v |
| V _{IL} | Low-Level Input Voltage | | 1.65 to 1.95 2.3 to 5.5 | | | 0.25 V _{CC} 0.3 V _{CC} | | 0.25 V _{CC} 0.3 V _{CC} | v |
| V _{OH} | High-Level Output Voltage V _{IN} = V _{IH} | I _{OH} = –100 μA | 1.65 1.8 2.3 3.0 4.5 | 1.55 1.7 2.2 2.9 4.4 | 1.65 1.8 2.3 3.0 4.5 | | 1.55 1.7 2.2 2.9 4.4 | | v |
| | | | 1.65 2.3 3.0 3.0 4.5 | 1.29 1.9 2.4 2.3 3.8 | 1.52 2.15 2.80 2.68 4.20 | | 1.29 1.9 2.4 2.3 3.8 | | v |
| V _{OL} | Low-Level Output Voltage V _{IN} = V _{IL} | I _{OL} = 100 μA | 1.65 1.8 2.3 3.0 4.5 | | 0.0 0.0 0.0 0.0 0.0 0.0 | 0.1 0.1 0.1 0.1 0.1 | | 0.1 0.1 0.1 0.1 0.1 | v |
| | | $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$ $I_{OL} = 16 \text{ mA}$ $I_{OL} = 24 \text{ mA}$ $I_{OL} = 32 \text{ mA}$ | 1.65 2.3 3.0 3.0 4.5 | | 0.08 0.10 0.15 0.22 0.22 | 0.24 0.30 0.40 0.55 0.55 | | 0.24 0.30 0.40 0.55 0.55 | v |
| I _{IN} | Input Leakage Current | V _{IN} = 5.5 V or GND | 0 to 5.5 | | | ±0.1 | | ±1.0 | μA |
| I _{OFF} | Power Off Leakage Current | V _{IN} = 5.5 V or V _{OUT} = 5.5 V | 0 | | | 1 | | 10 | μΑ |
| I _{CC} | Quiescent Supply Current | V _{IN} = 5.5 V or GND | 5.5 | | | 1 | | 10 | μA |

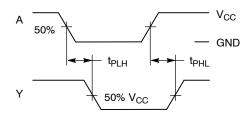
AC ELECTRICAL CHARACTERISTICS t_{R} = t_{F} = 2.5 ns; C_{L} = 50 pF; R_{L} = 500 Ω

| | | | | ٦ | 「 _A = 25° | C | –55°C ≤ T | գ ≤ 125°C | |
|------------------|-------------------|--------------------------------------|---------------------|-----|----------------------|-----|-----------|-----------|-------|
| Symbol | Parameter | Condition | V _{CC} (V) | Min | Тур | Max | Min | Max | Units |
| t _{PLH} | Propagation Delay | $R_L = 1 M\Omega, C_L = 15 pF$ | 1.8 ± 0.15 | 1.8 | 8.0 | 9.6 | 1.8 | 10.2 | ns |
| t _{PHL} | (Figure 3 and 4) | $R_L = 1 M\Omega, C_L = 15 pF$ | 2.5 ± 0.2 | 1.0 | 3.0 | 5.2 | 1.0 | 5.8 | |
| | | $R_L = 1 M\Omega, C_L = 15 pF$ | | 0.8 | 2.3 | 3.6 | 0.8 | 4.0 | |
| | | R_L = 500 Ω , C_L = 50 pF | 3.3 ± 0.3 | 1.2 | 3.0 | 4.6 | 1.2 | 5.1 | |
| | | $R_L = 1 M\Omega, C_L = 15 pF$ | | 0.5 | 1.8 | 2.9 | 0.5 | 3.2 | |
| | | R_L = 500 Ω , C_L = 50 pF | 5.0 ± 0.5 | 0.8 | 2.4 | 3.8 | 0.8 | 4.2 | 1 |

CAPACITIVE CHARACTERISTICS

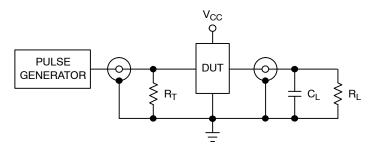
| Symbol | Parameter | Condition | Typical | Units |
|-----------------|--|--|---------|-------|
| C _{IN} | Input Capacitance | V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC} | 7.0 | pF |
| C _{PD} | Power Dissipation Capacitance (Note 6) | 10 MHz, V_{CC} = 3.3 V, V_I = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_I = 0 V or V_{CC} | 9 11 | pF |

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



 $\label{eq:propagation delays} \begin{array}{l} \textbf{PROPAGATION DELAYS} \\ t_{R} = t_{F} = 2.5 \text{ ns}, \mbox{ 10\% to } 90\%; \mbox{ f} = 1 \mbox{ MHz}; \mbox{ } t_{W} = 500 \mbox{ ns} \end{array}$





 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-----------------|----------------------------------|-----------------------|
| NL27WZ16DFT2G | SC-88/SC-70/SOT-363 (Pb-Free) | 3000 /Tape & Reel |
| NLV27WZ16DFT2G* | SC-88/SC-70/SOT-363 (Pb-Free) | 3000 /Tape & Reel |
| NL27WZ16DTT1G | TSOP-6 (Pb-Free) | 3000 /Tape & Reel |

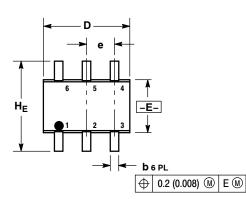
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

NL27WZ16

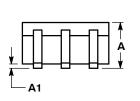
PACKAGE DIMENSIONS

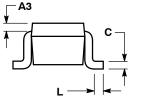
SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W**



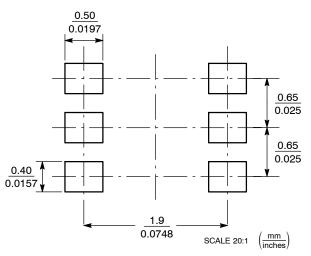
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|---------|------|--------|----------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.80 | 0.95 | 1.10 | 0.031 | 0.037 | 0.043 |
| A1 | 0.00 | 0.05 | 0.10 | 0.000 | 0.002 | 0.004 |
| A3 | | 0.20 RE | F | | 0.008 RI | EF |
| b | 0.10 | 0.21 | 0.30 | 0.004 | 0.008 | 0.012 |
| С | 0.10 | 0.14 | 0.25 | 0.004 | 0.005 | 0.010 |
| D | 1.80 | 2.00 | 2.20 | 0.070 | 0.078 | 0.086 |
| Е | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 |
| e | 0.65 BSC | | С | 0 | .026 BS | С |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 |
| HE | 2.00 | 2.10 | 2.20 | 0.078 | 0.082 | 0.086 |





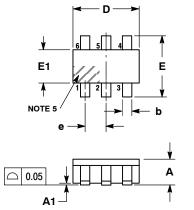
SOLDERING FOOTPRINT*

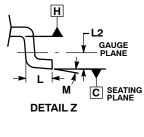


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 **ISSUE U**





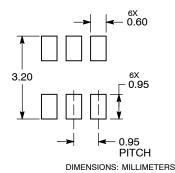


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. 2
- З.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR
- GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H. 5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

| | MILLIMETERS | | | | | |
|-----|-------------|------|------|--|--|--|
| DIM | MIN | NOM | MAX | | | |
| Α | 0.90 | 1.00 | 1.10 | | | |
| A1 | 0.01 | 0.06 | 0.10 | | | |
| b | 0.25 | 0.38 | 0.50 | | | |
| с | 0.10 | 0.18 | 0.26 | | | |
| D | 2.90 | 3.00 | 3.10 | | | |
| Е | 2.50 | 2.75 | 3.00 | | | |
| E1 | 1.30 | 1.50 | 1.70 | | | |
| e | 0.85 | 0.95 | 1.05 | | | |
| L | 0.20 | 0.40 | 0.60 | | | |
| L2 | 0.25 BSC | | | | | |
| М | 0° | - | 10° | | | |

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice ON Semiconductor and up are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights on or the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use pervised use as complex trendend reparation to the design or unauthorized use pervises. associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative